

RS Technologies Co., Ltd.

February 13, 2020



Code: 3445

Tokyo Stock Exchange First Section

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1. Company Overview



Company Overview

- Holds the top market share worldwide in semiconductor wafer reclamation at 30%
- Conducting a full-scale advance into the prime wafer business through a joint venture with a Chinese state-owned company
- Expanding into peripheral business fields expected to produce synergy through M&A

Company name	RS Technologies Co., Ltd.
Date of establishment	December 10, 2010
Corporate principles	"Respect the global environment, earn the trust of people, and constantly strive to create."
Business	Silicon Wafer Reclaim, Silicon Wafer Oxide Film Coating, Silicon Wafer Sales. Solar Power Station. Purchase and sale of used semiconductor equipment. Sale of chemical materials and semiconductor parts. Technical assistance and education service on semiconductor wafer manufacturing process.
Head office	NT Bldg. 12F, 1-47-1, Ohi, Shinagawa-ku, Tokyo 140-0014 JAPAN
Factory	26-2 Yamazaki, Sanbongi Otonashi, Osaki, Miyagi 989-6313 JAPAN
Capital	JPY 5,376 million (As of end December 2019)
President and CEO	Nagayoshi Ho
	RSTEC Semiconductor Taiwan Co.,Ltd. Founded in February 2014, Capital: NT \$300 million, Stake: 100%
	Beijing GRINM RS Semiconductor Materials Co., Ltd. Registered Capital US \$138 million, Stake 45%
Consolidated subsidiaries	Union Electronics Solutions Co., Ltd. Capital ¥27 million, Stake 100%
	Shandong GRINM Semiconductor Materials Co., Ltd. (Shandong GRITEK, Dezhou, Shandong) Registered Capital RMB 1,500 million, Stake 36%
	DG Technologies Co., Ltd. Capital ¥100 million, Stake 100%



History

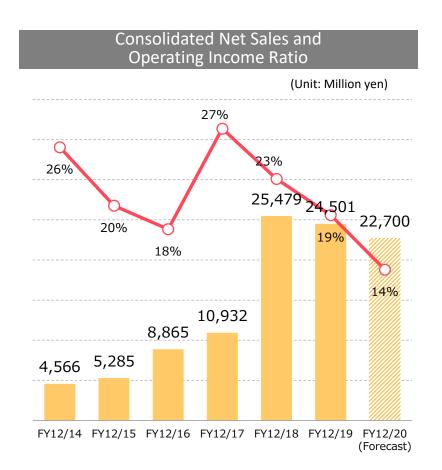
- Launched business in 2010 and holds top share worldwide in the silicon wafer reclamation business
- Converted a major Chinese prime wafer manufacturer into a consolidated subsidiary in 2018 and became a comprehensive manufacturer of wafers

Dec. 2010	RS Technologies established in Shinagawa-ku, Tokyo, with silicon wafer reclamation as its primary business
Jan. 2011	Operations begun at the Sanbongi Factory
Nov. 2011	Sanbongi Factory acquires ISO9001:2008 (quality management system) certification from UKAS
Mar. 2013	Equipment sales begun
Oct. 2013	Solar power business begun at the Sanbongi Factory
Feb. 2014	RSTEC Semiconductor Taiwan established as a subsidiary in Taiwan (currently a consolidated subsidiary)
Mar. 2015	RST listed on the Tokyo Stock Exchange Mothers Market
Jun. 2015	Fab8 completed at Sanbongi Factory, with cutting-edge equipment allowing reclamation of 18-inch wafers
Dec. 2015	Tainan Factory completed for RSTEC Semiconductor Taiwan (currently a consolidated subsidiary)
Sep. 2016	RST moved to the Tokyo Stock Exchange First Section
Dec. 2017	Joint venture agreement concluded with General Research Institute for Nonferrous Metals (GRINM) and Fujian Kuramoto
Jan. 2018	Beijing GRINM RS Semiconductor Materials Co., Ltd. (BGRS) established; Chinese prime wafer manufacturer Youyan Semiconductor Material Company Limited made a consolidated subsidiary
May 2018	Acquired 100% of shares at Union Electronics Solutions Co., Ltd. (distributor for Hitachi Power Semiconductor Device, Ltd.)
Aug. 2018	Established Shandong GRITEK Co., Ltd.
Jan. 2019	Acquired 100% of shares of DG Technologies Co., Ltd.
Dec. 2019	A four-party joint venture agreement concluded with General Research Institute for Nonferrous Metals (GRINM), Dezhou Huida Semiconductor Equity Investment Fund Partnership, and the City of Dezhou in Shandong
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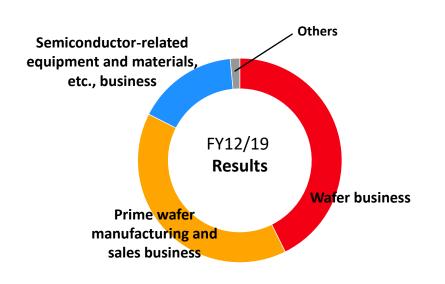


RS Technologies Today

- A comprehensive wafer manufacturer in the silicon wafer reclamation business and prime wafer business.
- Business has expanded into semiconductor-related equipment and materials, etc., business and solar business.
- The Company boasts the world's top share in the silicon wafer reclamation business and is expanding its prime wafer business in China for its domestic use.



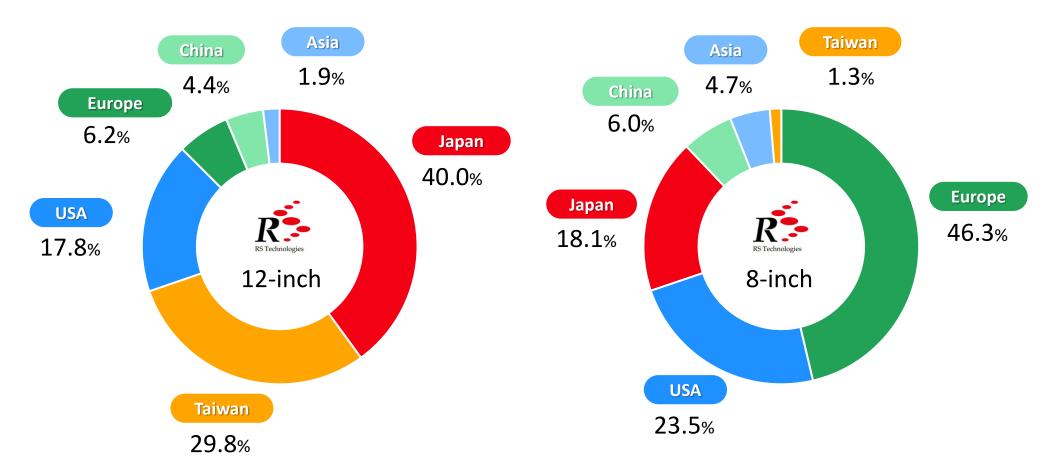
Results by Segment





Share of Total Shipments from the Silicon Wafer Reclamation Business

- The customers are major global semiconductor manufacturers, mainly in Japan, Taiwan, USA, and Europe.
- Capital investment decided to establish a new production base in China during FY2019 to respond to the expansion of future demand.





2. FY12/19 Results Summary



FY12/19 (Cumulative) Results summary

- Net sales have seen a fall in prime wafer business impacted by economic slowdown and YoY profit has fallen.
- In addition to the fall in sales above, operating income has suffered a YoY decrease due to costs to rectify past fiscal year reports and increase in personnel costs for enhancements to internal management system.

(million yen)	FY12/18	FY12/19 Initial forecast	FY12/19 Revised forecast (Announced Jan. 17, 2020)	FY12/19	Vs. Previous term	Against revised forecast
Net sales	25,478	28,688	24,500	24,501	-3.8%	+0.0%
Operating income	5,751	5,971	4,600	4,717	-18.0%	+2.5%
Operating income ratio	22.6%	20.8%	18.8%	19.3%	-3.3pt	+0.5pt
Ordinary income	6,141	6,151	5,400	5,416	-11.8%	+0.3%
Ordinary income ratio	24.1%	21.4%	22.0%	22.1%	-2.0pt	+0.1pt
Net income attributable to owners of the parent	3,620	3,621	3,000	3,035	-16.2%	+1.2%
Net income per share	294.80	282.72	233.83	236.98	-19.6%	+1.3%



FY12/19 (Cumulative) Results by Segment and Company

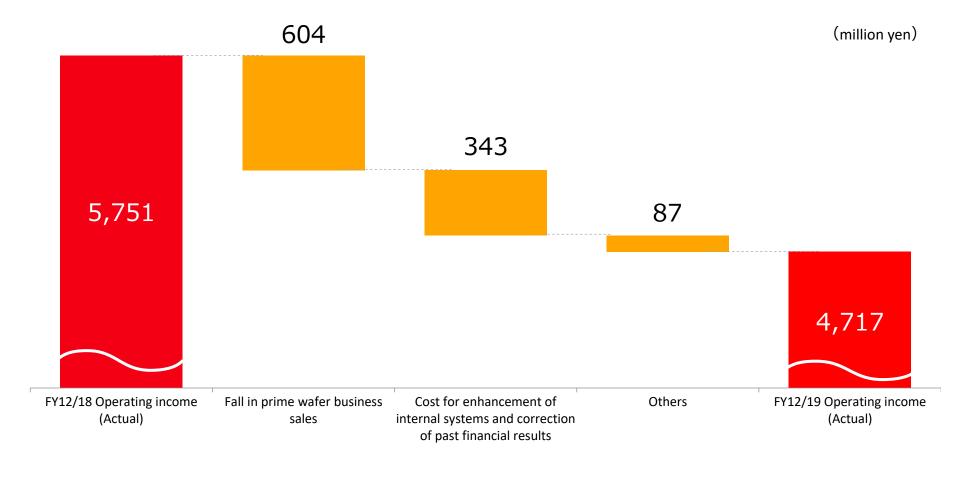
- Increase in profit has been secured in wafer business although net sales have fallen. Full production continues fueled by active demand.
- Prime wafer business has suffered a fall for both YoY sales and profit, affected by the slowdown of economy.
- YoY income has fallen for RS from a decrease in capital spending in the semiconductor market. In addition, profit has also fallen due to cost incurred for correction of previous financial results, and cost increase for enhancement of internal control systems.
- Taiwan subsidiary has enjoyed YoY increase in both sales and profit for increased production as a result of capital investment and increased demand from the customers.

	Wafer Busine	ess	Prime Wafer W and Sales Busin	_	Semiconductor Equipment, Ma Business		Others, Adj	ustments	Consolidated	Total
By Segment (million yen)		YoY		YoY		YoY		YoY		YoY
Net sales	10,776	-1.8%	10,058	-15.6%	4,047	+38.7%	-380	_	24,501	-3.8%
Operating income	4,081	+1.7%	1,503	-26.6%	171	-53.3%	-1,038	_	4,717	-18.0%
Operating income ratio	37.9	+1.3pt	14.9	-2.3pt	4.2	-8.3pt	_		19.3	-3.3pt
	RS		Taiwan Subsi	diary	Beijing Subsi	diary	Other Subsi		Consolidated	Total
By Company (million yen)		YoY		YoY		YoY		YoY		YoY
Net sales	9,447	-10.5%	3,464	+19.3%	10,058	-15.6%	1,532	- -	24,501	-3.8%
Operating income	1,989	-24.4%	1,185	+22.0%	1,564	-23.9%	-21	- -	4,717	-18.0%
Operating income ratio	21.1	-3.8pt	34.2	+0.8pt	15.5	-1.7pt	_	_	19.3	-3.3pt



FY12/19 (Cumulative) Factors Affecting Operating Income

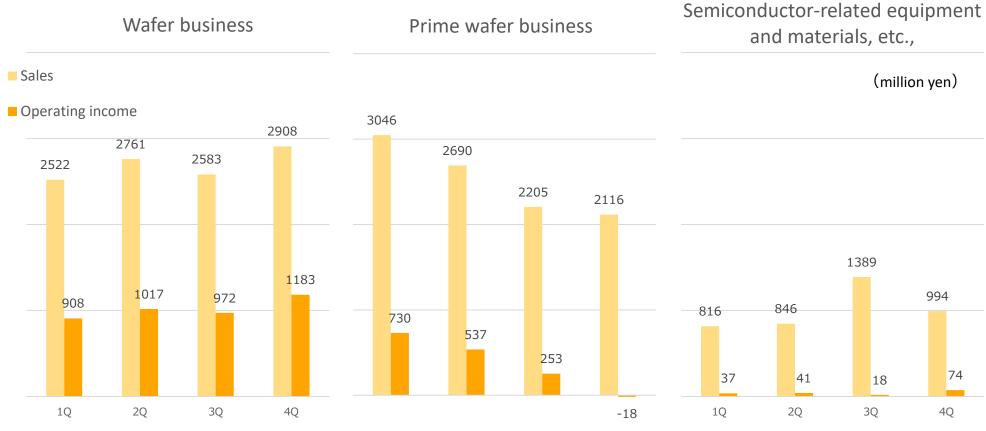
Operating income has suffered a fall in sales of prime wafer business impacted by the slowdown of economy, and a YoY fall in profit for increase in cost for internal system enhancement and cost for correction of previous financial results.





FY12/19 Quarterly Result Chart by Segment

- Wafer business is showing a stable trend for both sales and profit, from increase in demand from the customers.
- Prime wafer business has suffered a temporary decrease in sales affected by the slowdown of economy. R&D has begun for mass production of 12-inch prime wafers, with medium to long-term growth of the semiconductor market in sight.
- Semiconductor-related equipment and materials, etc. are stagnating from the impact of the fall in capital investment in the semiconductor market.

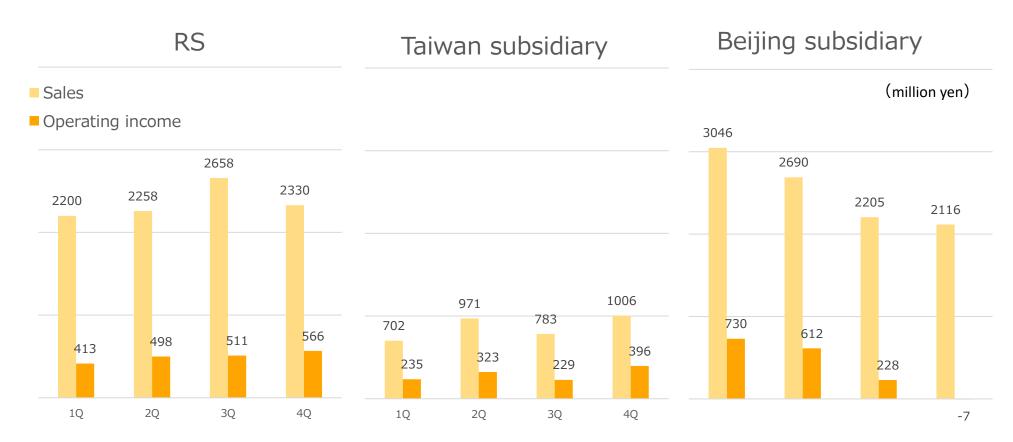




1Q 2Q 3Q 4Q

FY12/19 Quarterly Result Chart by Company

- RS and Taiwan subsidiary are showing stable trend for both sales and profit based on strong demand from the customers.
- Beijing subsidiary is suffering temporary decrease in sales affected by the slowdown of economy. R&D has begun for mass production of 12-inch prime wafers, with medium to long-term growth of the semiconductor market in sight.





Balance Sheet and Cash Flow

- Turning DG Technologies into a subsidiary, receipt of contribution and subsidies from Dezhou City Government, and the application of IFRS 16 (Leases) on overseas subsidiaries has resulted in an increase in Total Assets and Total Liabilities and net assets.
- Cashflow from investment activities has increased from the new plant construction investment in Dezhou City.

Consol	lidated	balance	e sheet
(million yon)	EV1	2/10	E

(million yen)	FY12/18	FY12/19
	Assets	
Current assets	26,074	32,760
Cash and cash equivalents	14,879	22,156
Notes and account receivable - trade	6,958	6,047
Merchandise and finished goods	1,343	1,713
Non-current assets	10,516	15,873
Property, plant, and equipment	8,963	14,635
Intangible assets	1,099	732
Investment and other assets	453	506
Total Assets	36,591	48,634
Current liabilities	4,979	7,252
Notes and account payable - trade	1,554	1,614
Interest bearing debts	976	1,730
Non-current liabilities	2,474	5,400
Long-term loans payable	1,848	2,232
Total Liabilities	7,453	12,652
Net assets	29,137	35,981
Total Liability and Net Assets	36,591	48,634

Cash flow

(million yen)	FY12/18	FY12/19
Cash flow from operating activities	2,669	9,015
Cash flow from investing activities	-22	-5,571
Cash flow from financing activities	9,550	4,206
Effect of exchange rate changes on cash and cash equivalents	-461	-404
Exchange gain on cash and cash equivalents	11,736	7,246
Cash and cash equivalents at beginning of year	2,916	14,652
Cash and cash equivalents at end of year	14,652	21,899

FY12/19 Efforts

- Converted DG Technologies into a 100% subsidiary in January 2019, to enhance semiconductor-related equipment and component, etc., business.
- Construction of a new prime wafer plant underway at Dezhou, Shandong.

Conversion of DG Technologies into a subsidiary

DGtec 株式会社DGテクノロジーズ

Company Name	DG Technologies Co., Ltd.	
Established	October 26, 1981	
Business	Manufacture and sale of consumable parts for semiconductor manufacturing equipment	
Location	3-4 Sunayama, Kamisu-shi, Ibaraki	
Capital	JPY 100,000 thousand (as of June 30, 2019)	
President & CEO	Nagayoshi Ho	

New prime wafer plant under construction

- Construction of a new plant for Shandong GRITEK (Consolidated subsidiary of RS in Dezhou, Shandong)
- Completion planned for Sep. 2020.



(Dec. 20, 2019)



3. Prime Wafer Business in China



Changes to the Investment Plan in China

- Demand for 12-inch prime wafers is expected to increase more than previously anticipated, accompanying the growth in semiconductor market.
- To respond to the above, partial changes have been made to the investment plan in China. (A decision to partially defer the plan to increase production of 8-inch prime wafers, and to make an early advance into the 12-inch wafer business.)

	Previous investment plan	New investment plan * Disclosed Dec. 18, 2019
Business environment	 Growth in power semiconductor demand is expected accompanying the growth in home appliance and automobile market. 	◆ Situation has changed where demand for 12-inch wafers is expected to increase more than previously anticipated, accompanying the growth of the semiconductor market.
Investment strategy	 Establish global quality in 8-inch prime wafers then enter 12-inch wafer business. 	 Partially review plans to install additional capacity for 8-inch wafers, Decide on earlier advance into 12-inch wafer business.
Investment plan	◆ 8-inch prime wafer production capacity of 220,000 wafers/month in 2021. (70.000 existing + 150,000 additional wafers)	 ♦ 8-inch prime wafer production capacity of 120,000 wafers/month in 2021. (70.000 existing + 50,000 additional wafers) ♦ Start R&D for mass production of 12-inch prime wafers → Install a test line: (10,000 wafers/month), target to achieve high-quality and mass production. ♦ Make investment for production base in China for 12-inch reclaimed wafer business.



Business Scheme for 12-inch Silicon Wafers in China

- Have set up a new joint venture with the City of Dezhou, and others.
- Initial risk associated with the entry into 12-inch silicon wafer business is suppressed by confining our initial stake.
- Start with a test line for 10,000 wafers/month and then aim for mass production of 300,000 wafers/month.

Investment scheme of the J/V

19.99% 19.99% 60.02% (No investment) **Dezhou City GRINM RST** Dezhou City Government backed Government fund*1 New Joint venture Subsidy, preferential infrastructure treatment

Joint venture agreement

- Joint venture agreement concluded among the 4 parties.
- There are 3 investors (GRINM, RST, and Dezhou City Government Fund)
- Dezhou City Government to provide support for infrastructure, etc.
- President of RST appointed concurrently as president of the new joint venture.

Business contents

- 12-inch prime wafer business (manufacturing, sales, development)
- 12-inch reclaimed wafer business*2
- *1. Dezhou Huida Semiconductor Equity Investment Fund Partnership
- *2. Please refer to P20 Decision to Invest in Reclaimed Wafer Business in China for details.



4. Reclaimed Wafer Business



Decision to Invest in Reclaimed Wafer Business in China

- Demand for reclaimed wafers is expected to increase, accompanying the growth of the semiconductor market.
- Decided to establish a new production base in China based on the expected increase in reclaimed wafer demand.
- Plan for 50,000 wafers/month as Phase 1 investment for the new production base. On-stream in 2022.

Environment for reclaimed wafer business

Capital investment decision made for a new production base in reclaimed wafer business

Growth of semiconductor market



Many investment plans for 12-inch semiconductor plants for memories, etc., have been announced.



Growth in demand for reclaimed 12-inch wafers can also be expected.

[Change in investment plan]

- Temporary defer installation of additional capacity for 8-inch prime wafers.
- Establish new production base for reclaimed wafers.

[Production capacity plan]

Phase 1 investment: 50,000 wafers/month

Phase 2 investment: 50,000 wafers/month (timing undecided)



New Demand in Reclaimed Wafer Business: Plans to construct new 12-inch semiconductor plants

- ■There are plans to construct new semiconductor plants to cope with the high demand for semiconductors for computerization of automobiles (in addition to digitization in automobiles, for EV and self-driving), etc., in Europe, USA, Japan, etc.
- Respond to new reclaimed wafer demand from new plants, by capital investment in Japan, Taiwan, and China.

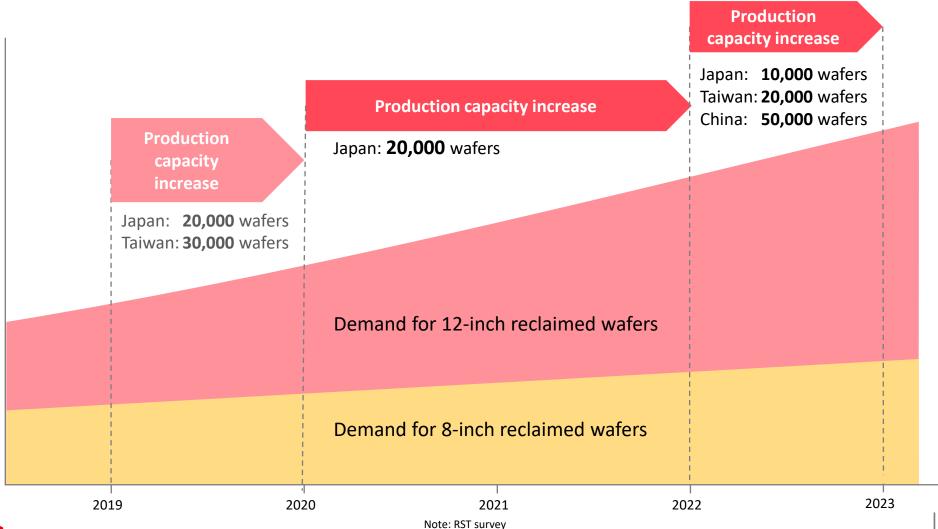




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Reclaimed Wafer Demand Outlook: Expansion to continue focused on 12-inch

■ Capacity enhancement of 30,000 wafers in Japan, 20,000 in Taiwan, and 50,000 in China are being planned between 2020 and 2022 to meet the expanding demand for reclaimed wafers.



5. Medium-Term Management Plan (2020 to 2023)



Summary of Medium-Term Management Plan (4 years)

- In the reclaimed wafer business, in addition to conventional bottle-neck investment, new investment for production bases will be made to respond to expansion of demand.
- New 8-inch prime wafer plants are expected to come on-stream sequentially from autumn 2020. R&D for mass production of 12-inch prime wafers will run concurrently.
- Target for net sales of 31.6 billion yen, operating income of 6.8 billion yen, and net income of 4.0 billion yen in FY2023.

	FY12/19	FY12/20	FY12/21	FY12/22	FY12/23
	Actual	Plan	Plan	Plan	Plan
Net sales	24,501	22,700	27,000	29,800	31,600
Operating income	4,717	3,200	4,800	6,100	6,800
Operating income ratio	19.3%	14.1%	17.8%	20.5%	21.5%
Ordinary income	5,416	3,400	5,000	6,400	6,900
Ordinary income ratio	22.1%	15.0%	18.5%	21.5%	21.8%
Net income attributable to owners of the parent	3,035	2,400	3,000	3,600	4,000
Net income per share (Yen)	236.98	187.07	233.84	280.61	311.79

Projected net income per share is determined based on the number of outstanding shares as of end-FY12/19.



Capital Investment Plan: Reclaimed Wafer Business

In the midst of expansion in global semiconductor demand, we have decided to invest in a new production base in China, in addition to capital investments in Japan and Taiwan.

Japan

Total investment: JPY 1.4 bil.

- Expand production capacity for 12inch reclaimed wafers.
- 2020 to 2022: JPY 1.4 bil. (30,000 wafers)

12-inch reclaimed wafer production capacity (wafers, monthly)

 $2019 \longrightarrow 270k \longrightarrow 280k$

FY2020	FY2021	FY2022
JPY 0.2 bil.	JPY 1 bil.	JPY 0.2 bil.

Taiwan

Total investment: JPY 1.4 bil.

- Expand production capacity and conduct refinement for 12-inch reclaimed wafers.
- 2020 to 2022: JPY 1.4 bil. (20,000 wafers)

12-inch reclaimed wafer production capacity (wafers, monthly)

FY2020	FY2021	FY2022
JPY 0.2 bil.	JPY 0.2 bil.	JPY 1 bil.

China

Total investment: JPY 3.8 bil.

- Investment to construct a new
 12-inch reclaimed wafer production base.
- Phase 1 investment (2020 to 2022):
 JPY 3.8 bil. (50,000 wafers)

12-inch reclaimed wafer production capacity (wafers, monthly)

		investment
FY2020	FY2021	FY2022
JPY 0.5 bil.	_	JPY 3.3 bil.



Capital Investment Plan: Prime Wafer Business

- Temporarily deferred capacity increase plans for 8-inch prime wafers (150k wafers/month \rightarrow 50k wafers/month). No change in start-up schedule.
- R&D started for 12-inch prime wafer mass production.

China

Total investment: JPY 14.0 bil.

- Expand production capacity for 8-inch prime wafers.
- Completion ceremony in Sep. 2020.

8-inch prime wafer production capacity (wafers, monthly)

2020 → 2021 **120k**

Investment period: 2019 to 2020, Operation to start sequentially from Autumn, 2020

FY2020	FY2021	FY2022
JPY 14.0 bil.	Not decided	Not decided

China

Test line investment: JPY 5 bil.

- R&D for 12-inch prime wafer mass production.
- Aim for mass production set-up for 300k wafers through a test line for 10k.

12-inch prime wafer production capacity (wafers, monthly)

2020 → 2021 → 202X **300k**

FY2020	FY2021	FY2022
JPY 0.5 bil.	JPY 4.5 bil.	Not decided

^{*}Test line for mass production R&D



FY12/20 Financial Result Outlook

- Consolidated results expected to show YoY decrease in income and profit caused by decrease in income and profit at Beijing subsidiary, foreign exchange impact on RS and Taiwan subsidiary, and increase in various costs.
- Although RS is expecting a firm demand for reclaimed wafers, YoY decrease in income and profit is expected from assuming strong YoY Japanese yen exchange rate transition and from increase of various costs.
- Although firm demand for reclaimed wafers is expected for Taiwan subsidiary, YoY increase in income but decrease in profit is expected from depreciation on capital investments and increase in various costs.

■ YoY decrease in income and profit is expected for Beijing subsidiary, impacted by the slowdown of economy and effects of plant relocation.

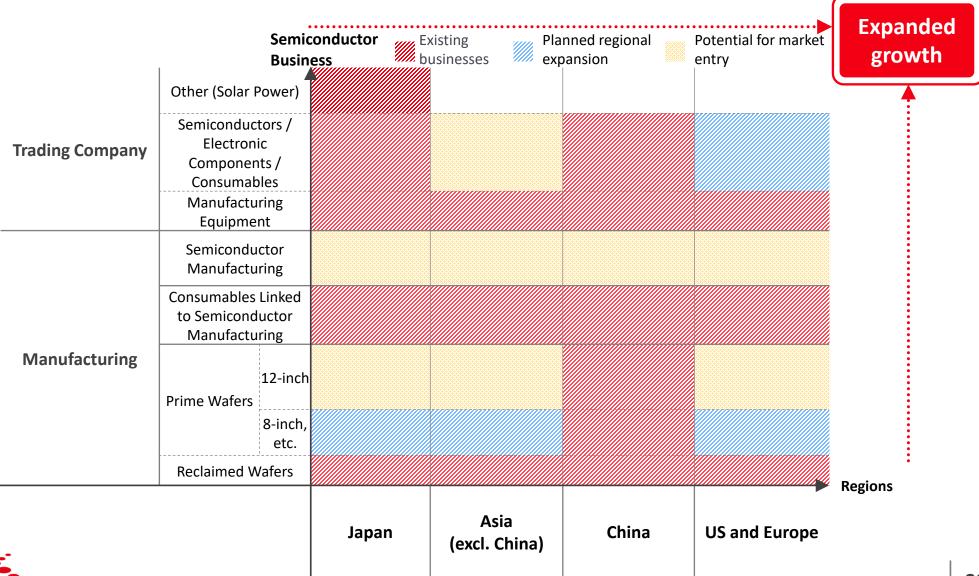
	FY12/19 (Jan. to Dec. 2019)	FY12/20 (Jan. to Dec. 2020)	Yo	PΥ
(million yen)	Full year actual results	Full year forecast	YoY	YoY%
Net sales	24,501	22,700	-1,801	-7.4%
Operating income	4,717	3,200	-1,517	-32.2%
Operating income ratio	19.3%	14.1%	-5.2pt	
Ordinary income	5,416	3,400	-2,016	-37.2%
Ordinary income ratio	22.1%	15.0%	-7.1pt	
Net income attributable to owners of the parent	3,035	2,400	-635	-20.9%
Net income per share	236.98 yen	187.07 yen	-49.91	-21.1%
Annual dividend	15 yen	15 yen	_	_

	RS	Taiwan subsidiary		ary	Beijing subsidiary		Other subsidiaries Consolidated total		otal
(million yen)		YoY		YoY		YoY	Elim. of Intra-co transactions.*	L .	YoY
Net sales	9,300	-1.6%	4,000	+15.5%	6,900	-31.4%	2,500	22,700	-7.4%
Operating income	1,700	-14.5%	1,000	-15.6%	200	-87.2%	300	3,200	-32.2%
Operating income ratio	18.3%	-2.8pt	25.0%	-9.2pt	2.9%	-12.6pt	-	14.1%	-5.2pt



RS Technologies' Aims

Steady expansion of business domains and regions



Appendix



Strengths of CEO Nagayoshi Ho

- President and CEO Nagayoshi Ho has knowledge gained from over 20 years in Japan, as well as strengths in worldwide sales, business networking, partnerships, and financing.
- President Ho has assembled a team of professionals from a broad range of fields including advanced technology and finance.



Nagayoshi Ho, center front (taken September 2016 at TSE)

Nagayoshi Ho

Born 1970 in Fujian Province, China Completed Josai International University Graduate Program

Specialty fields:

M&A, business alliances

(successful M&As with more than 10 companies)

1998 Established Eiki Shoji Co., Ltd.

2010 Established and appointed president of RTS (current position)

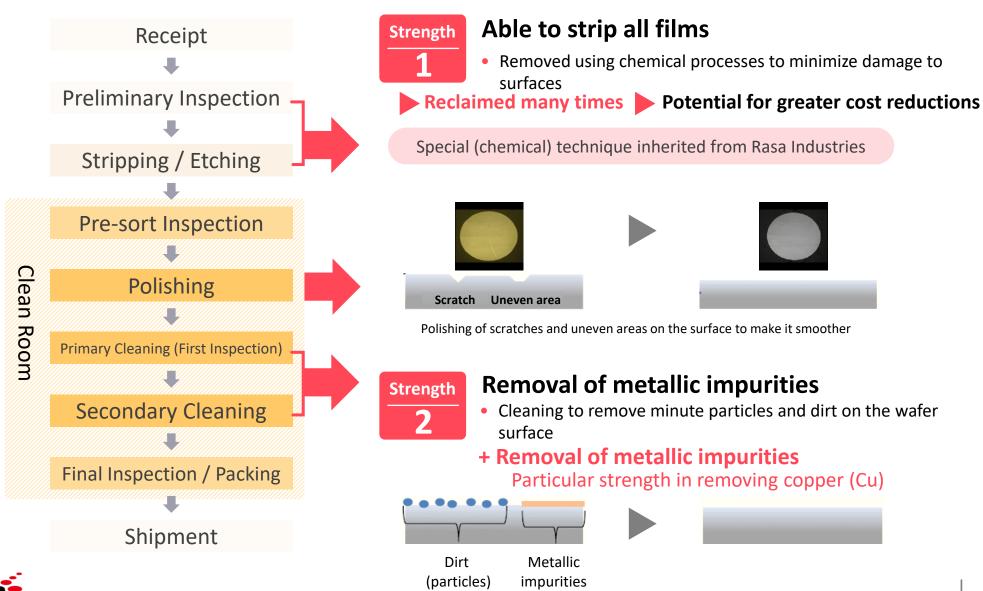
Favorite maxim: Where there is a will, there is a way

Supplementary information:

Nagayoshi Ho came to Japan after graduating high school. He has invested in more than 20 companies in Japan and abroad. In addition to semiconductors, he has experience investing in a range of businesses, including investment funds, trade, hotels, IT, and agriculture. He has traveled the world promoting his belief that Japanese manufacturing is the best in the world.



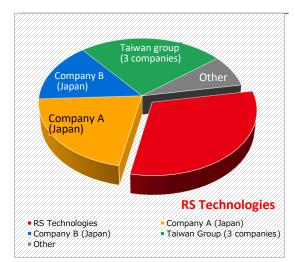
Reclaimed Wafer Business (1)



Reclaimed Wafer Business (2)

Increasing Share of the Reclaimed Market

RS Technologies' Share of the 12-inch Reclaimed Market



A new plant in Taiwan and expansion of the Sanbongi Factory increased production capacity, increasing our market share to 33%.

We will further enhance production capacity at both plants by using empty factories at Sanbongi, and utilizing business partnerships, M&A, and other means.

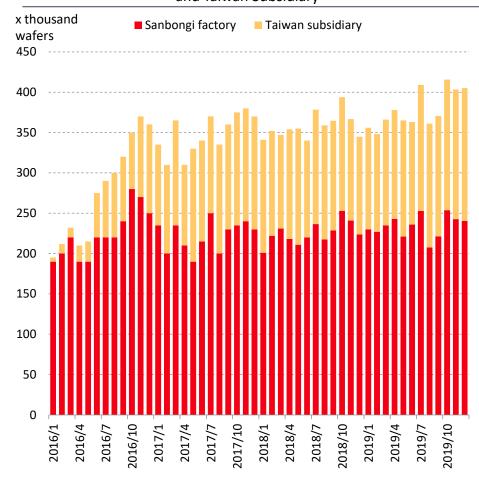
Note: RTS survey

	FY12/15 1H	FY12/15 2H	FY12/16	FY12/17	FY12/18	FY12/19
RST Group Production Capacity	180,000 wafers	240,000 wafers	280,000 wafers	300,000 wafers	340,000 wafers	400,000 wafers
RST Group Market Share	19%	24%	29%	30%	31%	33%

Note: RTS survey

Shipments from the Sanbongi Factory and Taiwan Subsidiary (2016-2019)

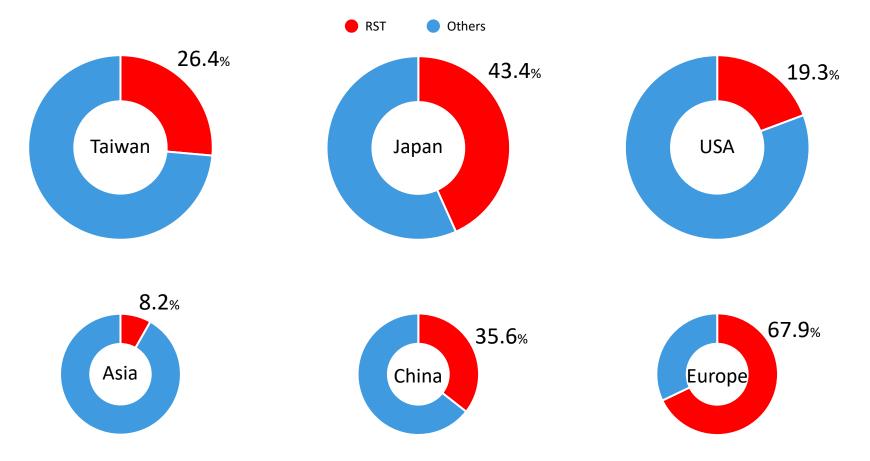
Shipments of 12-inch Wafers from the Sanbongi Factory and Taiwan Subsidiary





RST Share of Reclaimed Wafers by Region: 12-inch

- RST holds the global top share in the reclaimed wafer market.
- Factories are in Miyagi Prefecture (Sanbongi Factory) and Taiwan (Tainan Factory).
- Demand for reclaimed wafers is large and both Sanbongi and Tainan Factories continue to operate at full capacity.



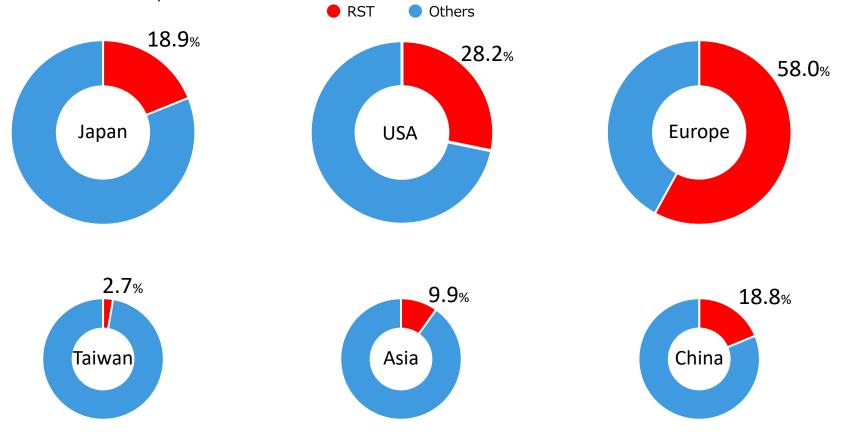


Notes: Based on wafer numbers reported in a study conducted by RST (fiscal 2018)

RST Share of Reclaimed Wafers by Region: 8-inch

- Factory in Miyagi Prefecture (Sanbongi Factory).
- Customers for 8-inch are centered on devices for automobile systems, power semiconductors, etc., that are not affected by business conditions.

■ Market share stands slightly less than 60% for European manufacturers, slightly less than 30% in USA, and slightly less than 20% in Japan and China.

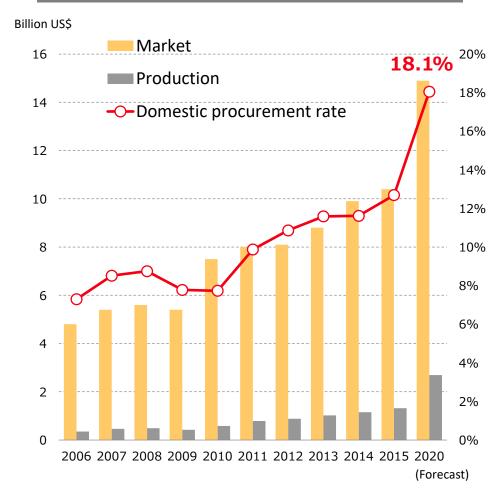




Notes: Based on wafer numbers reported in a study conducted by RST (fiscal 2018)

Regarding China Manufacturing 2025

Trend in China's Semiconductor Market and Production



Source: SEMI, August 2017 Issue, Report 1

China's semiconductor consumption has grown to account for 40% of the world's total.

However, its domestic production rate is around 15% of the consumption.

Raising the domestic production rate has become **an important policy issue.**

June 2014

Promotion of a National IC Industry Development Guidelines

May 2015

China Manufacturing 2025

[Excerpt] (Made in China 2025)

China is aiming to improve the self-sufficiency rate for ICs in the nation to 40% in 2020, and boost the rate further to 70% in 2025.



The target is domestic production rate of **40%** by 2020, and **70%** by 2025.

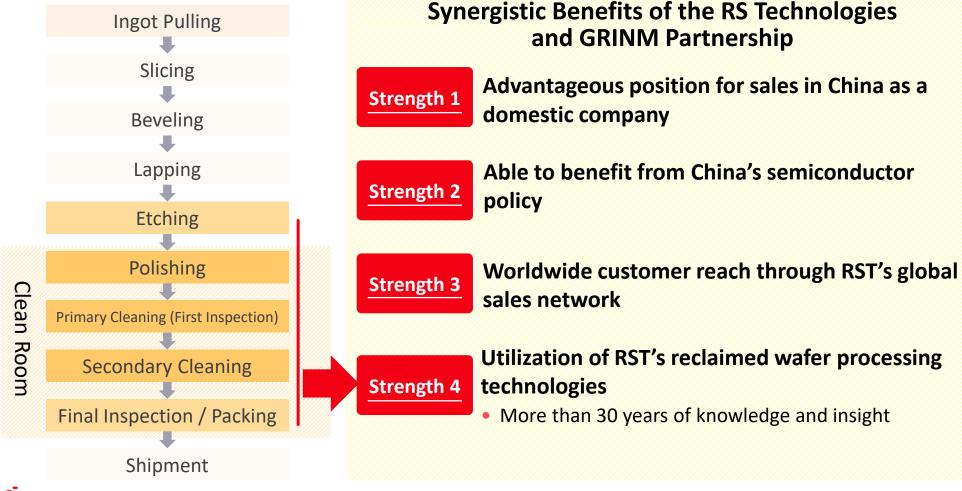
Current condition:

Issues concerning quality remain despite rapid enhancement of production capacity.



Entry into Prime Wafer Business

■ RS Technologies has established a joint venture with Chinese state-owned company General Research Institute for Nonferrous Metals (GRINM) and is developing its semiconductor business as a domestic Chinese company.





Regarding our Joint Venture Partner in China

- Established in 1952, GRINM is the largest state-owned research institute in the field of non-ferrous metals in China.
- Out of the roughly 13 million companies in China, about 300 thousand are state owned.
 - Out of these, about 88 are directly owned by the central national government and GRINM is one of these.
- GRINM is a research institute through which government, industry and science come together. Nonferrous metal policies of the central national government are transmitted through GRINM.
- GRINM established operating companies that serve as evidence of its successful research. Currently, 34 of these companies exist.
- GRITEK, a subsidiary of Beijing GRINM RS Semiconductor Materials Co., Ltd. (BGRS), an RST joint venture, was established as GRINM's first operating company in 2001.





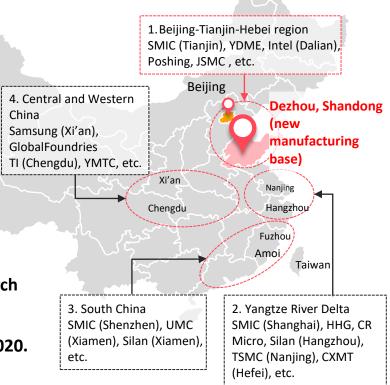
Partnership with the City of Dezhou in Shandong, China Subsidiary established for factory construction

Background of Partnership

- Worldwide invitations for major semiconductor manufacturers to set up factories in the area are gaining momentum. Several semiconductor manufacturers are located nearby, making the area a prime location (see image on the right)
- GRITEK will be able to offer plentiful benefits, including low-cost company housing and reduced utility expenses.
- 3. Science and engineering universities are located nearby, providing favorable circumstances for acquiring superior human resources
- 4. Land expandable to a maximum of about 500,000m² (initially 200,000m²) has been procured, allowing for adequate response to future business progress in China

History and current status

- 1. New company (GRITEK) established on August 23, 2018.
- 2. Ground-breaking ceremony for new factory in City of Dezhou held on March 19, 2019.
- 3. Buildings currently under construction. Scheduled for completion in 1Q 2020.
- 4. A four-party joint venture agreement concluded with General Research Institute for Nonferrous Metals (GRINM), Dezhou Huida Semiconductor Equity Investment Fund Partnership, and the City of Dezhou in Shandong in Dec. 2019.

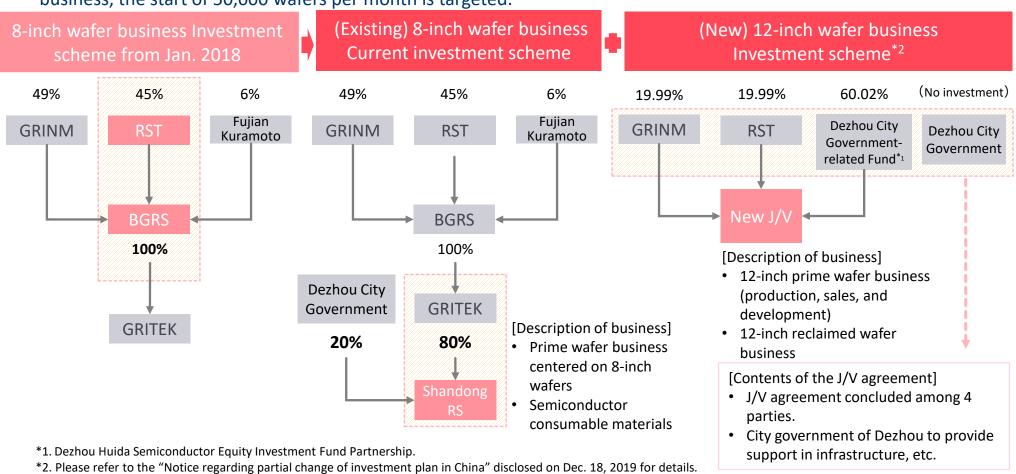




China Business Investment Scheme

Listed stakes are the final and in accordance with investment agreements.

- To undertake new 12-inch wafer business, a new joint venture was established with GRINM, the City Government of Dezhou, etc. Initial risk has been suppressed by confining our initial stake.
- Prime wafer business undertaken by the new joint venture aims to establish a mass production system of 300,000 wafers per month, starting with a test line of 10,000 wafers per month. As Phase 1 investment for the reclaimed wafer business, the start of 50,000 wafers per month is targeted.



Year-by-Year Results

(million yen)	FY12/13	FY12/14	FY12/15	FY12/16	FY12/17	FY12/18	FY12/19
Net sales	3,475	4,566	5,285	8,864	10,932	25,478	24,501
Gross profit	1,173	1,820	1,852	2,544	4,252	8,366	7,940
Selling, general and administrative expenses	471	654	791	958	1,269	2,615	3,223
Operating income	703	1,166	1,061	1,585	2,982	5,751	4,717
Ordinary income	819	1,247	770	1,444	3,159	6,141	5,416
Net income*	525	664	143	861	2,113	3,620	3,035
Dividend (Yen)	-	-	-	10	5	10	15
Capital investment	338	3,503	4,665	209	95	1,328	4,809
Depreciation	87	103	326	682	714	1,298	1,814
Research and development expenses	1	6	11	85	183	501	449
Number of employees (Regular employees)	152	191	265	373	434	1,159	1,277



^{*}Net income attributable to owners of the parent company.

Principal Financial Statements

		i	i	i	i					
(million yen)	FY12/13*	FY12/14	FY12/15	FY12/16	FY12/17	FY12/18	FY12/19			
Assets										
Current Assets	1,811	2,759	3,732	5,348	7,388	26,074	32,760			
Cash and cash equivalent	397	1,190	1,842	1,952	3,243	14,879	22,156			
Notes and accounts receivable - trade	681	696	795	2,531	2,916	6,958	6,047			
Merchandise and finished goods	396	376	361	348	446	1,343	1,713			
Non-current assets	508	4,064	5,845	5,333	4,843	10,516	15,873			
Property, plant and equipment	461	3,918	5,667	5,152	4,674	8,963	14,635			
Intangible assets	19	15	29	23	19	1,099	732			
Investments and other assets	27	130	148	158	149	453	506			
Total Assets	2,320	6,823	9,577	10,682	12,231	36,591	48,634			
Liabilities										
Current liabilities	960	2,292	2,295	2,993	3,370	4,979	7,252			
Notes and accounts payable - trade	138	151	186	283	398	1,554	1,614			
Interest-bearing debt	136	827	1,216	1,538	1,276	976	1,730			
Non-current liabilities	709	2,934	4,798	4,317	3,335	2,474	5,400			
Long-term loans payable	615	2,925	4,079	3,620	2,767	1,848	2,232			
Total Liabilities	1,670	5,227	7,093	7,310	6,705	7,453	12,652			
Net Assets										
Net assets	649	1,596	2,483	3,371	5,526	29,137	35,981			
Total Liabilities and Net Assets	2,320	6,823	9,577	10,682	12,231	36,591	48,634			

Performance by Segment

(million yen)	FY12/13	FY12/14	FY12/15*	FY12/16*	FY12/17*	FY12/18	FY12/19
Net sales							
Wafer business	3,347	4,414	5,107	7,144	9,487	10,973	10,776
Prime wafer manufacturing and sales business	_	_	_	_	<u></u>	11,918	10,058
Purchases and sales of semiconductor equipment business	_	_	_	1,654	1,393	2,918	4,047
Other, adjustments	127	151	178	66	52	-331	-380
Segment profit							
Wafer business	916	1,444	1,377	1,765	3,396	4,011	4,081
Prime wafer manufacturing and sales business	_	_	_	_	<u></u>	2,048	1,503
Purchases and sales of semiconductor equipment business	_	_	_	230	130	366	171
Other, adjustments	-214	-278	-316	-409	-543	-675	-1,038
Segment assets							
Wafer business	1,337	5,040	6,987	5,657	8,120	9,150	10,336
Prime wafer manufacturing and sales business	_	_	_	_	_	21,313	29,311
Purchases and sales of semiconductor equipment business	_	_	_	1,137	1,305	1,939	3,179
Other, adjustments	982	1,783	2,589	3,887	2,805	4,315	5,806



Forward-looking Statements

The content of these materials was prepared based on generally recognized economic potential and certain assumptions considered reasonable by the Company but is subject to revision without notice due to changes in various business environments affecting management.

Materials and information provided for this announcement contain forward-looking statements. This information is based on assumptions pertaining to the current outlook, forecasts and risks, and contains uncertainties that could result in different outcomes.

Even in the case of new information, future events, or other relevant matters, the Company is under no obligation to update or revise the forward-looking statements contained in this material.

